

SUBMINIATURE SOLID STATE LAMP

PRELIMINARY SPEC

Part Number: AM2520SURCK09

Hyper Red

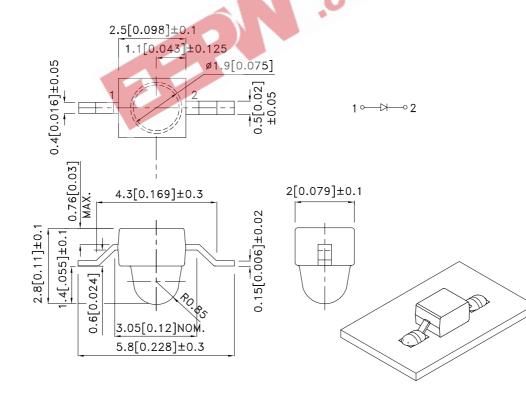
Features

- SUBMINIA TURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- PACKAGE: 1000PCS / REEL.
- RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.

4. Specifications are subject to change without notice.

5. The device has a single mounting surface. The device must be mounted according to the specifications.





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 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.L.LI
 ERP: 1202000703

Selection Guide

Part No.	Dice	Dice Lens Type Iv (mcd) [2] @ 20mA			Viewing Angle [1]
			Min.	Тур.	201/2
AM2520SURCK09	Hyper Red (InGaAIP)	WATER CLEAR	480	1400	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650	. 4	nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	635	34	nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28	-	nm	IF=20mA
С	Capacitance	Hyper Red	35	10.	pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	IF=20mA
lr	Reverse Current	Hyper Red		10	uA	V _R =5V

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

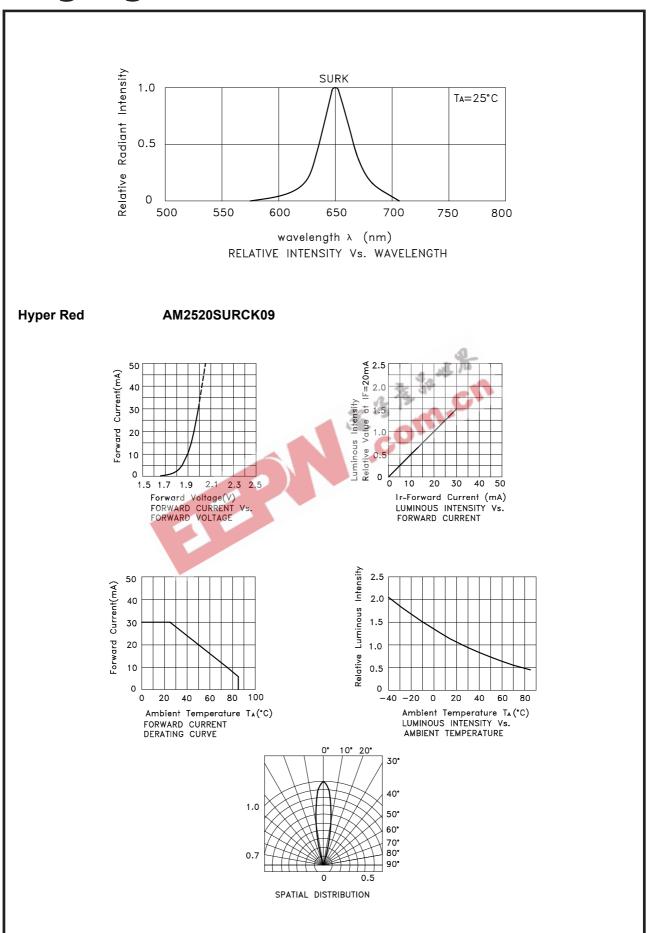
Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	185	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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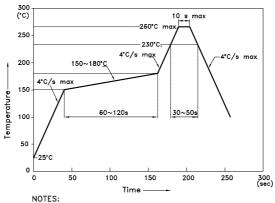


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Reflow Soldering Profile For Lead-free SMT Process.

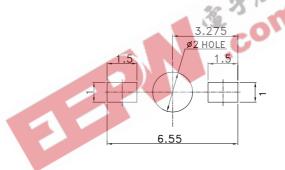


- NOTES:

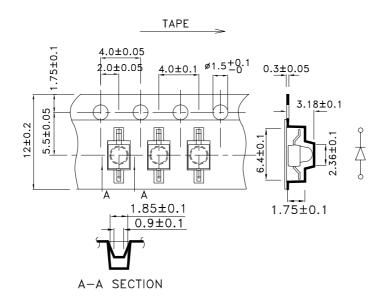
 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



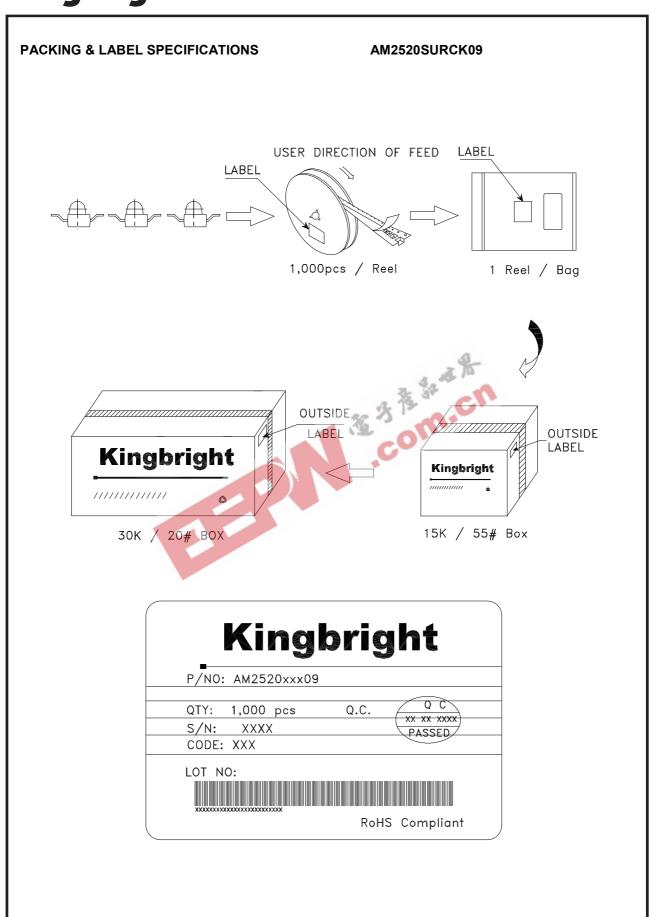
Tape Specifications (Units: mm)



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